



#9/a
3/4/03 2811
PATENT
Customer No. 22,852
Attorney Docket No. 04329.2686

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

YOSHIAKI SUGIZAKI) Group Art Unit: 2811
Serial No: 09/972,855) Examiner: Junghwa M. Im
Filed: October 10, 2001)
For: SEMICONDUCTOR DEVICE)

Commissioner for Patents
Washington, DC 20231

Sir:

AMENDMENT

In reply to the Office Action dated November 21, 2002, the non-fee period for response extending to February 21, 2003, please amend the application as follows.

IN THE SPECIFICATION:

Please amend the specification as follows:

Please replace the paragraph beginning on page 12, line 3 and continuing to page 13, line 4, with the following amended paragraph:

In FIG. 1A, a semiconductor chip 1 is mounted on a wiring substrate 7 through a conductive bump 4 so that a formation surface 2 of the semiconductor chip 1 on which a semiconductor element (internal circuit) is formed faces to a surface of the chip 1 side of the wiring substrate 7, which surface is on the side of the semiconductor chip 1, namely

RECEIVED
FEB 25 2003
TECHNOLOGY CENTER 2800

FINNEGAN
HENDERSON
FARABOW
GARRETT &
DUNNER LLP

1300 I Street, NW
Washington, DC 20005
202.408.4000
Fax 202.408.4400
www.finnegan.com